

Fig. 1 (Prior Art)

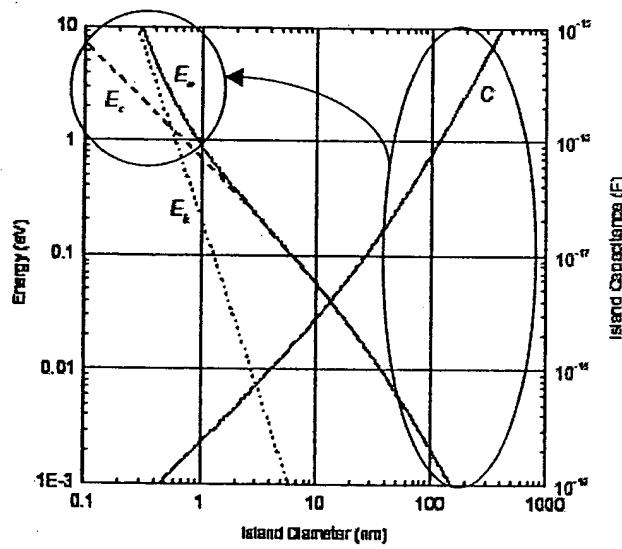


Fig. 2 (Prior Art)

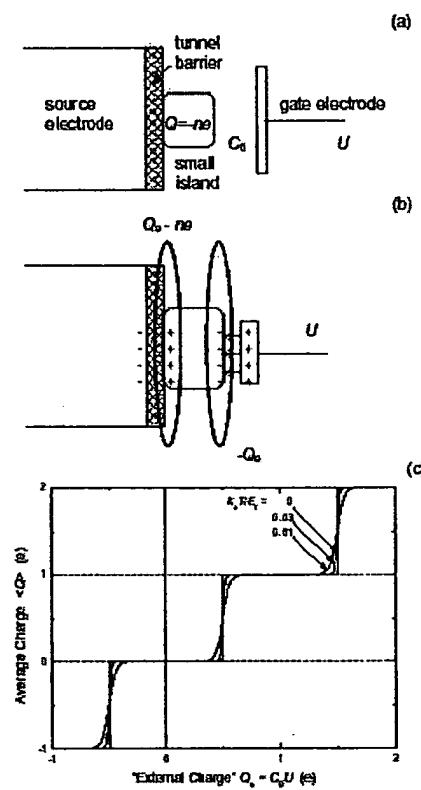


Fig. 3 (Prior Art)

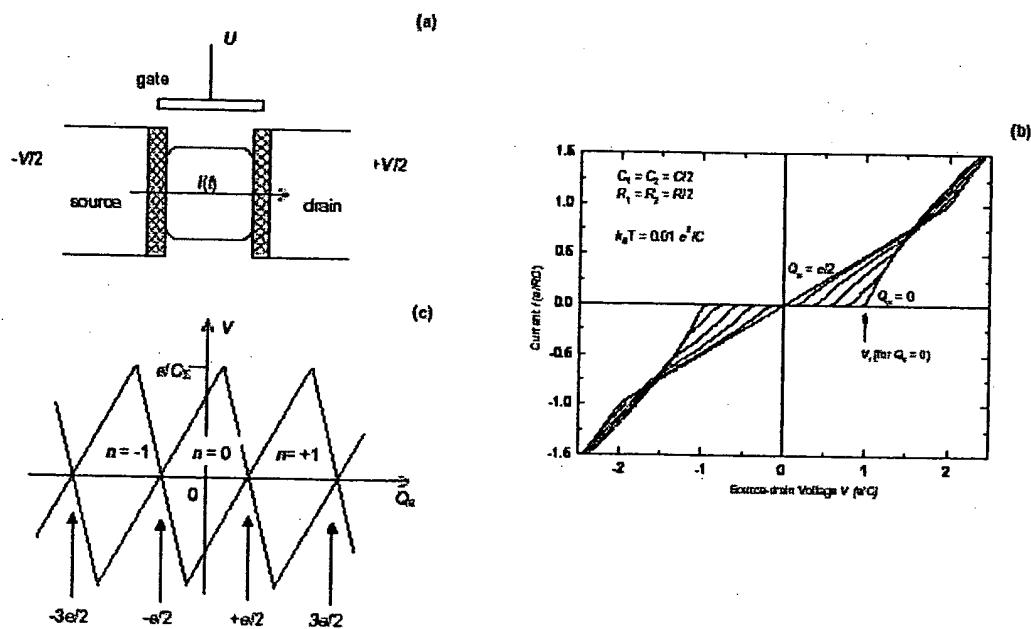


Fig. 4 (Prior Art)

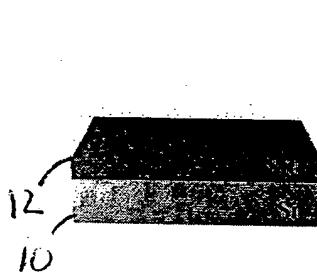


Figure 5a

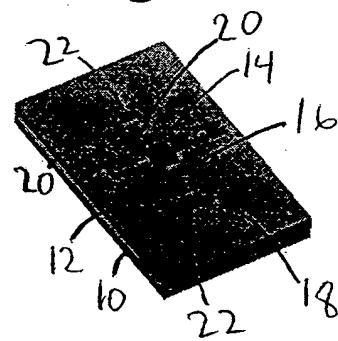


Figure 5b

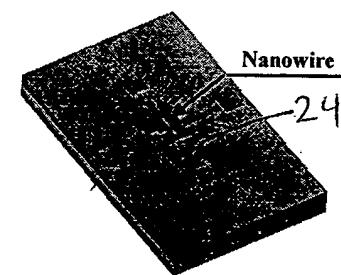


Figure 5c

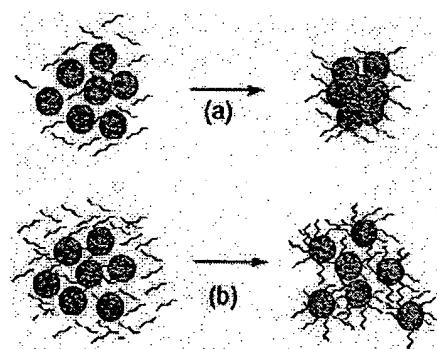


Fig. 6

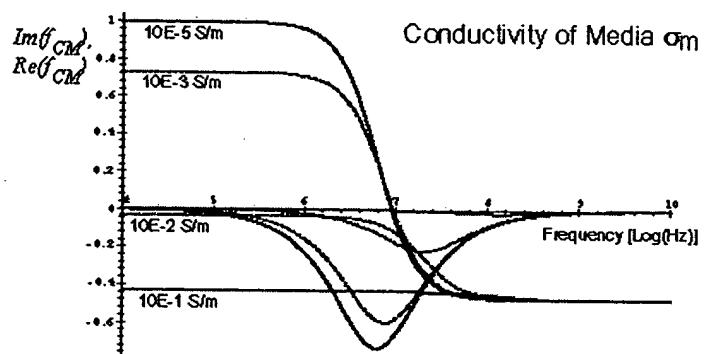


Fig. 7

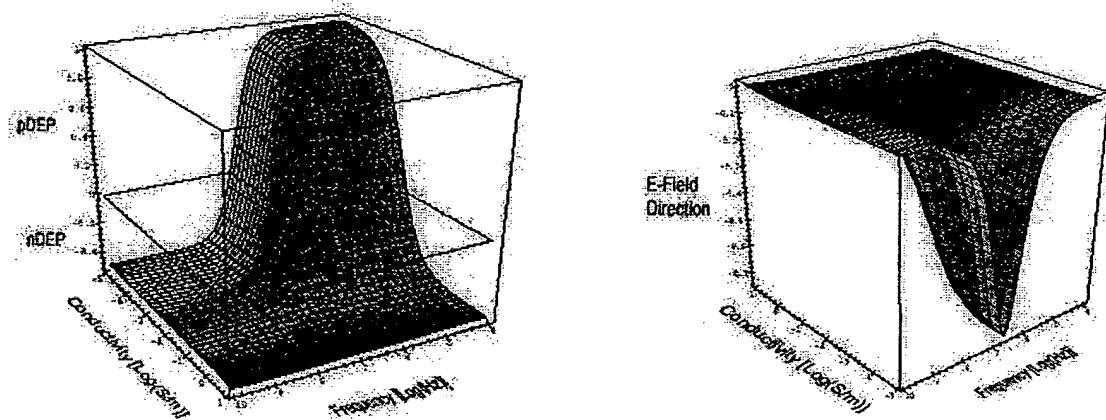


Fig. 8

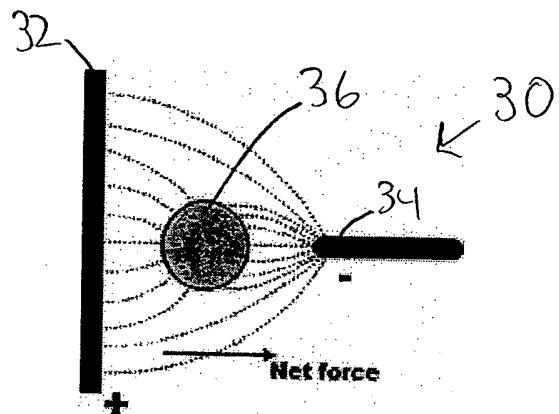


Fig. 9

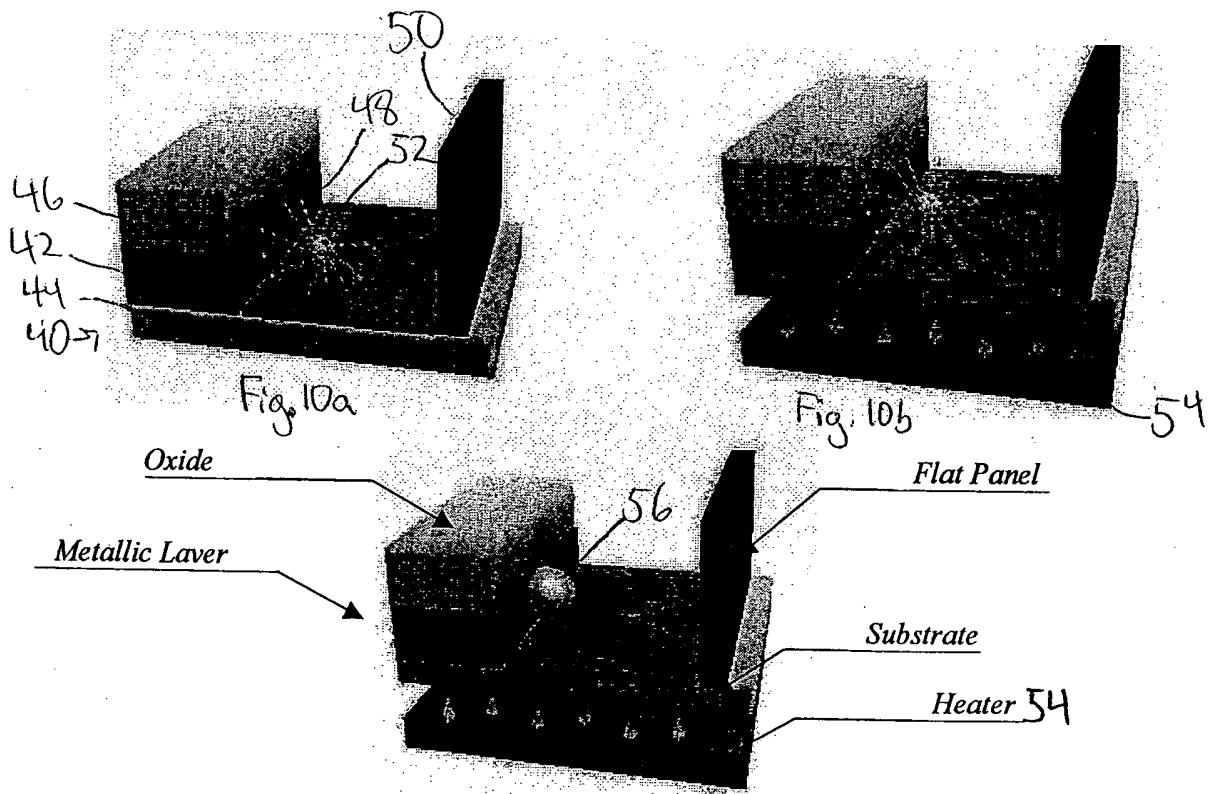


Fig. 10c

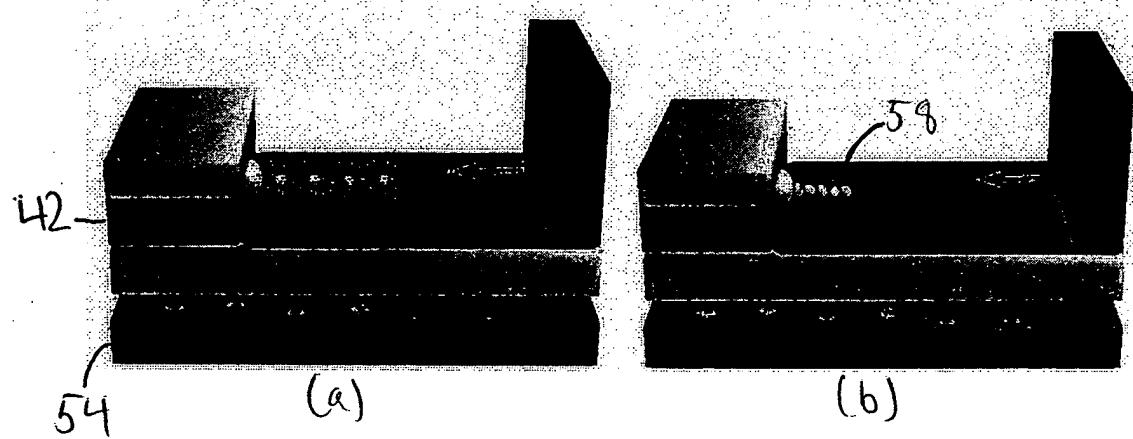


Fig. 11

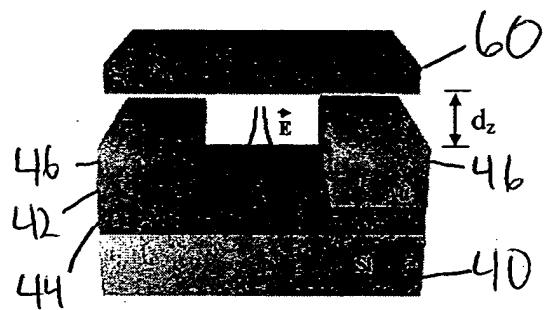


Fig. 12

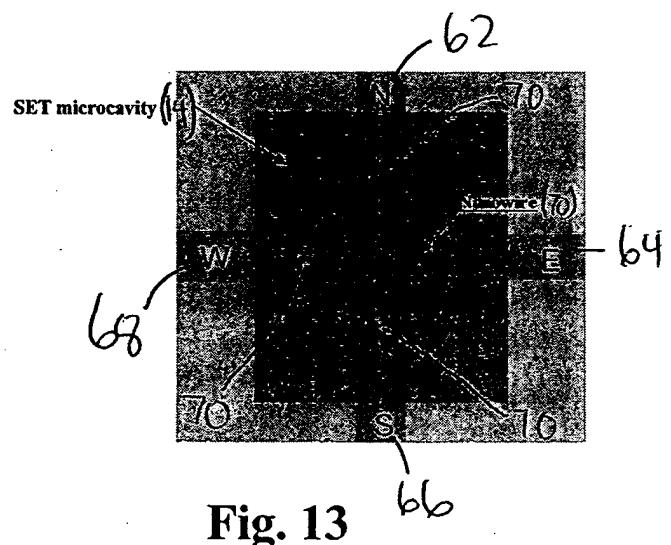


Fig. 13

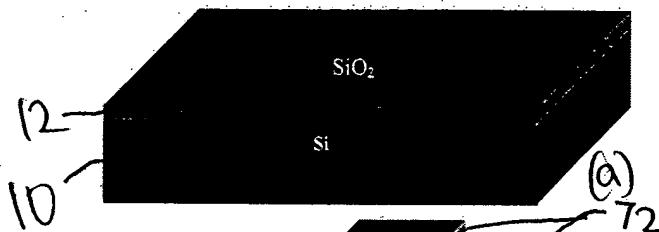


Fig. 14

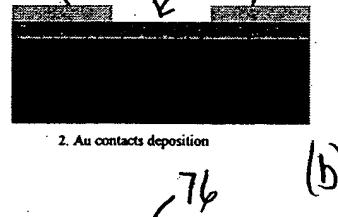
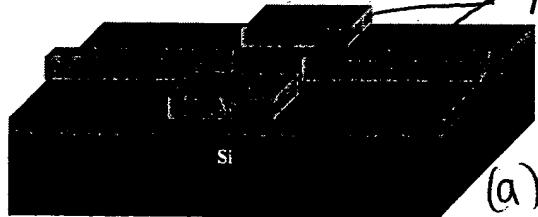


Fig. 15

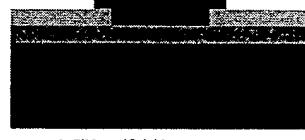
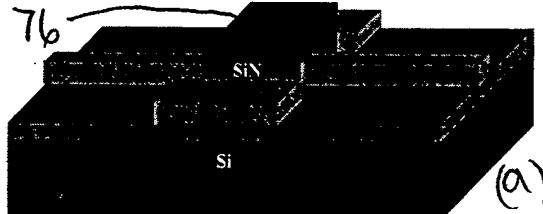


Fig. 16

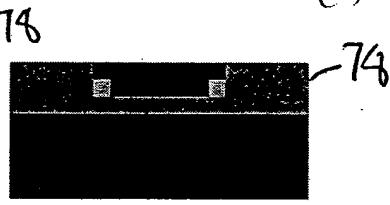
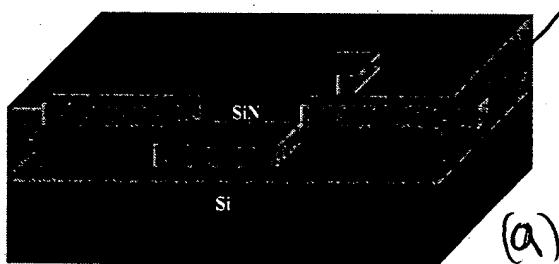
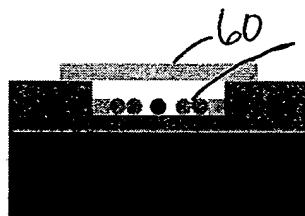
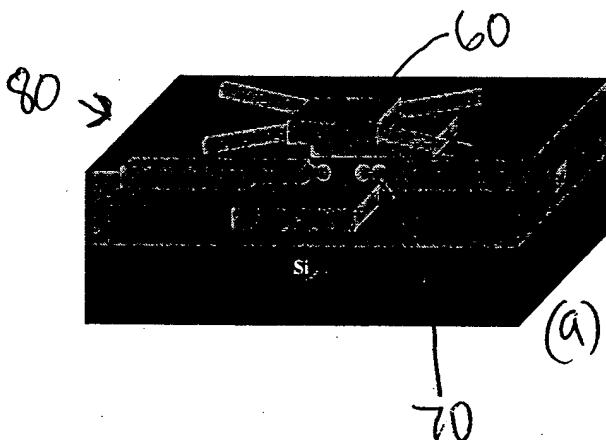


Fig. 17



5. Au top electrode deposition, SiN
sacrificial layer removal and SET
realization by dielectrophoresis

Fig. 18